

ABSTRACT

The invention provides a bump structure whose mounting position, shape, and size are favorably controlled and to a method of manufacturing the same. The bump structure of the invention can be provided on an insulating layer and includes a protruding part made of resin obtained by hardening a liquid material and a conductive layer that covers the protruding part. The protruding part can be obtained by forming a liquid-repelling part with a liquid-repelling characteristic for the liquid material and a liquid-attracting part that is more wettable than the liquid-repelling part for the liquid material on an upper surface on the insulating layer, discharging the liquid material onto the liquid-attracting part, and then hardening the liquid material.